MMDL770T1

Schottky Barrier Diode

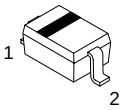
Schottky barrier diodes are designed primarily for high–efficiency UHF and VHF detector applications. Readily available to many other fast switching RF and digital applications.

- Extremely Low Minority Carrier Lifetime
- Very Low Capacitance – 1.0 pF @ 20 V
- Low Reverse Leakage – 200 nA (max)
- High Reverse Voltage – 70 Volts (min)
- Available in 8 mm Tape and Reel
- Device Marking: 5H

ON Semiconductor™

http://onsemi.com

1.0 pF SCHOTTKY BARRIER DIODE



PLASTIC
SOD–323
CASE 477

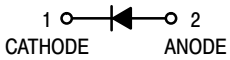
MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V_R	Reverse Voltage	70	Vdc

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
P_D	Total Device Dissipation FR–5 Board,* T_A = 25°C Derate above 25°C	200 1.57	mW mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	°C/W
T_J, T_{stg}	Junction and Storage Temperature Range	–55 to +150	°C

*FR–5 Minimum Pad



ORDERING INFORMATION

Device	Package	Shipping
MMDL770T1	SOD–323	3000 / Tape & Reel

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage (I_R = 10 μA)	$V_{(BR)R}$	70	–	–	Volts
Diode Capacitance (V_R = 20 Volts, f = 1.0 MHZ)	C_T	–	0.5	1.0	pF
Reverse Leakage (V_R = 35 V)	I_R	–	9.0	200	nAdc
Forward Voltage (I_F = 1.0 mAdc) (I_F = 10 mA)	V_F	–	0.7	1.0	Vdc

TYPICAL CHARACTERISTICS

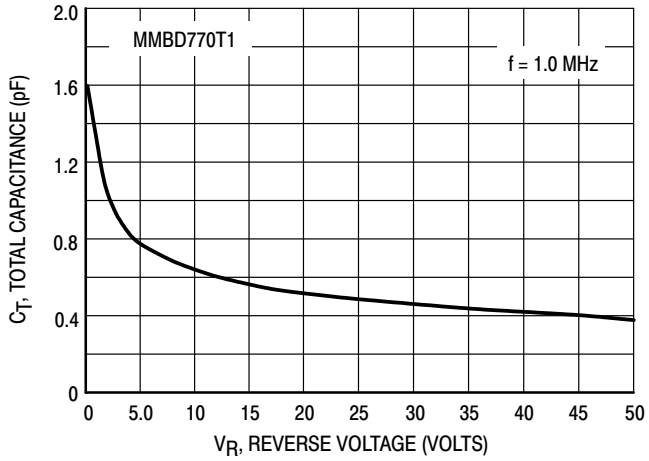


Figure 1. Total Capacitance

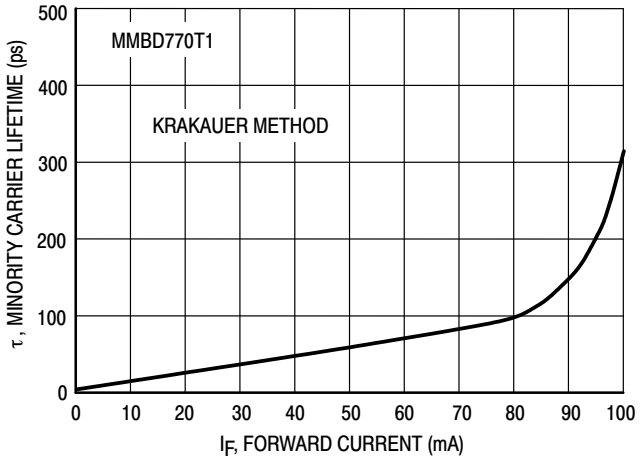


Figure 2. Minority Carrier Lifetime

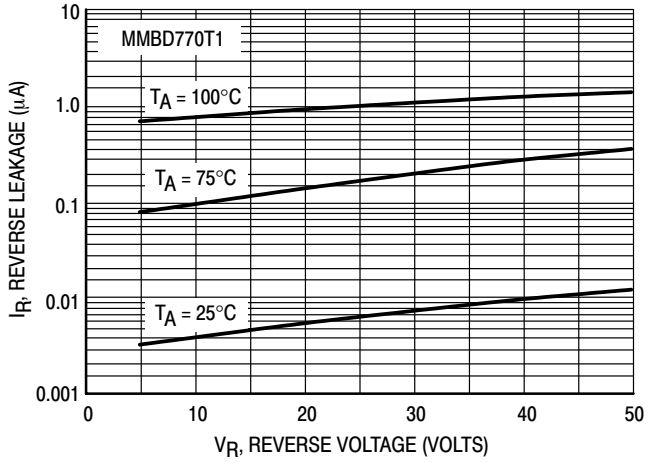


Figure 3. Reverse Leakage

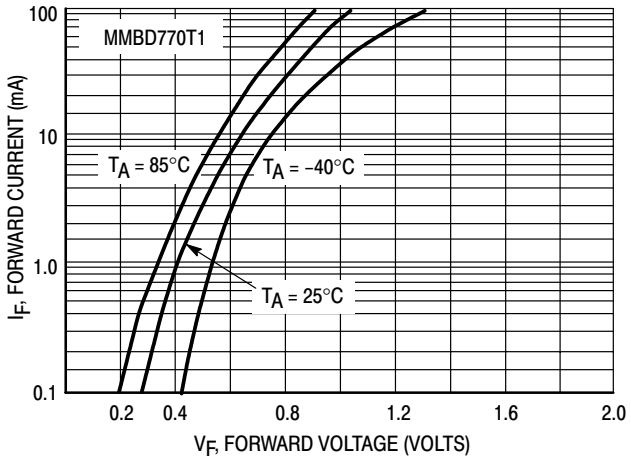
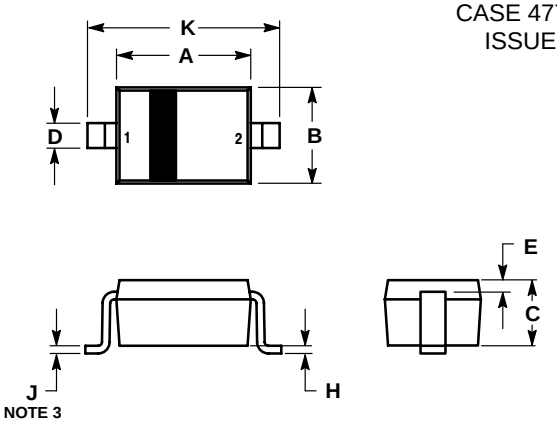


Figure 4. Forward Voltage

PACKAGE DIMENSIONS

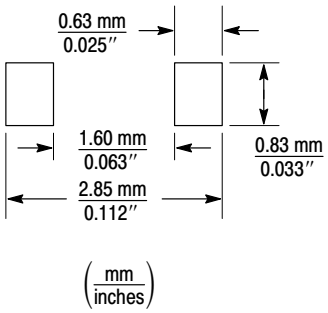
SOD–323
PLASTIC PACKAGE
CASE 477–02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	1.60	1.80	0.063	0.071
B	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
E	0.15 REF		0.006 REF	
H	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106

STYLE 1:
PIN 1. CATHODE
2. ANODE



SOD–323
Soldering Footprint

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada
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Sales Representative.